

<b>Notice of References Cited</b>		Application/Control No.	Applicant(s)/Patent Under Reexamination	
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Examiner		Art Unit		Page 1 of 1
Alonzo Chambliss		2814		

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	C	US-6,294,444	09-2001	Ueno, Katsunori	438/514
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	V	D.B. Beach, " Design of low-temperature thermal chemical vapor deposition processes ", IBM J. REs. Develop., November 1990, Vol. 34, No. 6,
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.